This Sheet Has Been Replaced



# Controlled Profile Multiple Chip Modules

## Abstract

A multiple chip module architecture capable of forming structures having selectable aspect ratios which themselves form the basis for higher levels of integrations in analogous manner. The modular architecture having first level modules (16) and second level module (17) uses a flexible interconnect (22) of patterned copper on polymer to successibly reorient the connection plane between successive levels (for example, a reorientation of the wiring plane from that of contacts 7 to that of contacts 23), permitting the selective stacking of module levels to create the desired aspect ratio of the multiple chip module. Interconnection between levels, for example by contacts (23) and pads (24) may be accomplished by solder reflow, direct dendritic bonding, or connection through a dendritic interposer.

Figure 3